Laboratory Data Sheet

OXY-BOND 105

August 2015

PRODUCT DESCRIPTION

OXY-BOND 105 is an exceptional epoxy formulation, recommended for lower temperature or wet industrial bonding applications where fast curing is required. This clear, two-part, medium-viscosity system mixes easily at room temperature, contains no solvents, and is suitable for high performance structural-bonding applications where the combination of very fast room temperature cure coupled with low shrinkage and excellent mechanical and electrical properties is required. It develops strong, tough bonds to metals, phenolic plastics, polyesters, glass and glass fabrics, hardboards and forestry products, ceramics, rubber, masonry materials, and other construction materials. Fully cured Oxy-Bond 105 is an excellent electrical insulator and provides superior resistance to vapors and gases, water, galvanic action, petroleum fuels, salt solutions, and many other organic and inorganic compounds.

APPLICATIONS

High speed bonding and repairs at low temperatures. Ideal for assembly lines and various production applications such as staking, fillet bonds, and general industrial repairs. Used in component assembly, appliances, electronics, and fiber optics. Sets in five minutes, reaches full strength in about one hour.

Physical Properties

Color:	Transparent, Light Straw
Operating Temperature Range, °C:	-60 to 125
Specific Grav. (mixed/resin/hardener.)	1.14/1.17/1.13
Hardness, Shore D:	74
Impact, Izod, ft. lbs/Inch of Notch:	2.1
Dielectric Strength, Volts/Mil:	415

Handling Characteristics

Viscosity of Resin @ 25 °C, cps	11,000 – 15,000
Viscosity of Hardener @ 25 °C, cps	10,000 – 16,000
Mixed Viscosity @ 25°C, cps:	14,000 – 17,000
Mix-Ratio by Volume, Resin to Hardener:	1 to 1
Pot Life, Small Mass:	4 to 5 minutes
Cure Schedule, Shore D @ 25°C	After 10 min. 28 After 30 min. 68 After 60 min. 74

Storage

Store below 25°C out of sunlight and in original unopened containers. Refer to packaging specific quote for shelf life information.

Data Ranges

The data contained herein may be reported as a typical value and/or range. Values are based on actual test data and are verified on a periodic basis.

Note

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